

MM54HC03/MM74HC03 Quad 2-Input Open Drain NAND Gate

General Description

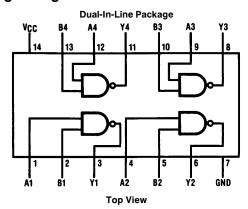
These NAND gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs. All devices have high noise immunity and the ability to drive 10 LS-TTL loads. The 54HC/74HC logic family is functionally as well as pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to $V_{\rm CC}$ and ground.

As with standard 54HC/74HC push-pull outputs there are diodes to both V_{CC} and ground. Therefore the output should not be pulled above V_{CC} as it would be clamped to one diode voltage above $V_{CC}.$ This diode is added to enhance electrostatic protection.

Features

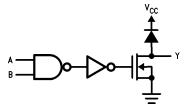
- Typical propagation delay: 12 ns
- Wide power supply range: 2-6V
- Low quiescent current: 20 µA maximum (74HC Series)
- Low input current: 1 µA maximum
- Fanout of 10 LS-TTL loads

Connection and Logic Diagrams



TL/F/5295-1

Order Number MM54HC03 or MM74HC03



TL/F/5295-2

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

ncations.
0.5 to + 7.0 V
V _{CC} +1.5V
$V_{CC} + 0.5V$
\pm 20 mA
\pm 25 mA
\pm 50 mA
to +150°C
600 mW
500 mW
260°C

Operating Conditions								
	Min	Max	Units					
Supply Voltage (V _{CC})	2	6	V					
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V					
Operating Temp. Range (T _A)								
MM74HC	-40	+85	°C					
MM54HC	-55	+125	°C					
Input Rise or Fall Times								
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns					
$V_{CC} = 4.5V$		500	ns					
$V_{CC} = 6.0V$		400	ns					

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		T _A =25°C		T _A = 25°C		74HC T _A = -40 to 85°C	54HC T _A = -55 to 125°C	Units
				Тур		Guaranteed	1					
V _{IH}	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V V				
V _{IL}	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V				
V _{OL}	Minimum Low Level Output Voltage	$V_{IN} = V_{IH}$ $ I_{OUT} \le 20 \mu A$ $R_L = \infty$	2.0V 4.5V 6.0V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V V				
		$V_{IN} = V_{IH}$ $ I_{OUT} \le 4.0 \text{ mA}$ $ I_{OUT} \le 5.2 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V V				
I _{LKG}	Maximum High Level Output Leakage Current	V _{IN} =V _{IH} or V _{IL} V _{OUT} =V _{CC}	6.0V		0.5	5	10	μА				
I _{IN}	Maximum Input Current	V _{IN} =V _{CC} or GND	6.0V		±0.1	±1.0	±1.0	μΑ				
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		2.0	20	40	μΑ				

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V \pm 10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC}=5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

^{**} V_{IL} limits are currently tested at 20% of V_{CC} . The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics $v_{CC}\!=\!5\text{V},\,T_{A}\!=\!25^{\circ}\text{C},\,C_{L}\!=\!15\,\text{pF},\,t_{r}\!=\!t_{f}\!=\!6\,\text{ns}$

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t _{PZL} , t _{PLZ}	Maximum Propagation Delay	$R_L = 1 K\Omega$	10	20	ns

AC Electrical Characteristics

 V_{CC} =2.0V to 6.0V, C_L =50 pF, t_r = t_f =6 ns (unless otherwise specified)

Symbol	Parameter	Conditions	v _{cc}	T _A =25°C		74HC T _A = -40 to 85°C	54HC T _A = -55 to 125°C	Units	
				Тур	Guaranteed Limits]	
t _{PLZ} , t _{PZL}	Maximum Propagation	$R_L=1 K\Omega$	2.0V	63	125	158	186	ns	
	Delay		4.5V	13	25	32	37	ns	
			6.0V	11	21	27	32	ns	
t _{THL}	Maximum Output		2.0V	30	75	95	110	ns	
	Fall Time		4.5V	8	15	19	22	ns	
			6.0V	7	13	16	19	ns	
C _{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		20				pF	
C _{IN}	Maximum Input Capacitance			5	10	10	10	pF	

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$. The power dissipated by R_L is not included.

Physical Dimensions inches (millimeters) 0.785 (19.939) MAX [14] [13] [12] [11] [10] [9] [8] 0.025 (0.635) 0.220-0.310 RAD (5.588-7.874) 1 2 3 4 5 6 7 0.290-0.320 0.005 0.200 GLASS SEALANT (5.080) MAX 0.020-0.060 (7.366-8.128) (D.127) MIN 0.060 ±0.005 (1.524 ±0.127) 0.180 MA (0.508-1.524) (4.572) ∮95° ±5 0.008-0.012 10° MAX (0.203-0.305) 0.310-0.410 D.018 ±0.003 0 125-0 200 (7.874-10.41) 0.098 (0.457 ±0.076) (3.175 - 5.080)(2.489) 0.100 ±0.010 MAX BOTH ENDS (2.540 ±0.254) (3.81) J14A (REV G) MIN Ceramic Dual-In-Line Package (J) Order Number MM54HC03J or MM74HC03J NS Package Number J14A (6.350 ± 0.010 (6.350 ± 0.254) 1 2 3 4 5 6 7 0.092 (2.337) DIA 0.030 MAX (0.762) DEPTH 0.075±0.015 (1 905±0.381) 0.014 - 0.023 (0.356 - 0.584) 0.100 ± 0.010 (2.540 ± 0.254) 0.050 ± 0.010 (1.270 - 0.254) TYF Molded Dual-In-Line Package (N) Order Number MM74HC03N

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NS Package Number N14A

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



National Semiconductor National Semiconducto Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018

National Semiconductor Europe

Fax: (+49) 0-180-530 85 86 Fax: (+49) U-18U-35U oo oo Email: onjwege tevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tei: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80

National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon

Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960

National Semiconductor Japan Ltd.
Tel: 81-043-299-2309
Fax: 81-043-299-2408